System Model # SDW-636-CVP

Dimension: 3400mm x1200mm x 190mm

POWER 1: Voltage=208V /Amp=6A POWER 2: Voltage=110V /Amp=20A

Wafer Size=6"(150mm)

Spin unit:

Spin motor type=Brushless DC servo motor

Rotation =0 to 6000 rpm

Rotation precision: Rotation range linearity Reproducibility

 $10^{\sim}600$:
 Within +1,-5rpm
 Within ± 4rpm

 $600^{\sim}1000$:
 Within ± 0.5%
 Within ± 0.5%

 $1000^{\sim}6000$:
 Within ± 0.3%
 Within ± 0.4%

Chemical system:

Coater resist supply= bellows pump

Coater resist filter= Millipore 0.2um

Spin unit purge=N2 purge

Coater resist nozzle= FEP capillary nozzle

Coater solvent supply= central supply(not pump)

Spin unit N2 blow/ purge system= Operates by factory line pressure.

Oven unit N2 purge system= Operates by factory line pressure.

Oven system:

Bake method= Contact bake with hot plate

Oven plate= Aluminum processed with hard alumite.

Hot plate temperature regulation=50 to 250°C set in 1°C increments

Bake/cooling time= 0 to 999 sec per 1 zone set in 1 sec increment

Contact strengthen processing:

Method= HMDS vapor rocessing in a semi-closed chamber

HMDS bubbler = Carries out N2 bubbling with the stainless steel bubbler at the bubbling tank.

HMDS vapor supply= The HMDS is forced fed to the chamber by the N2 pressure bubbling.

Program date= 9 date(D1 to D9)